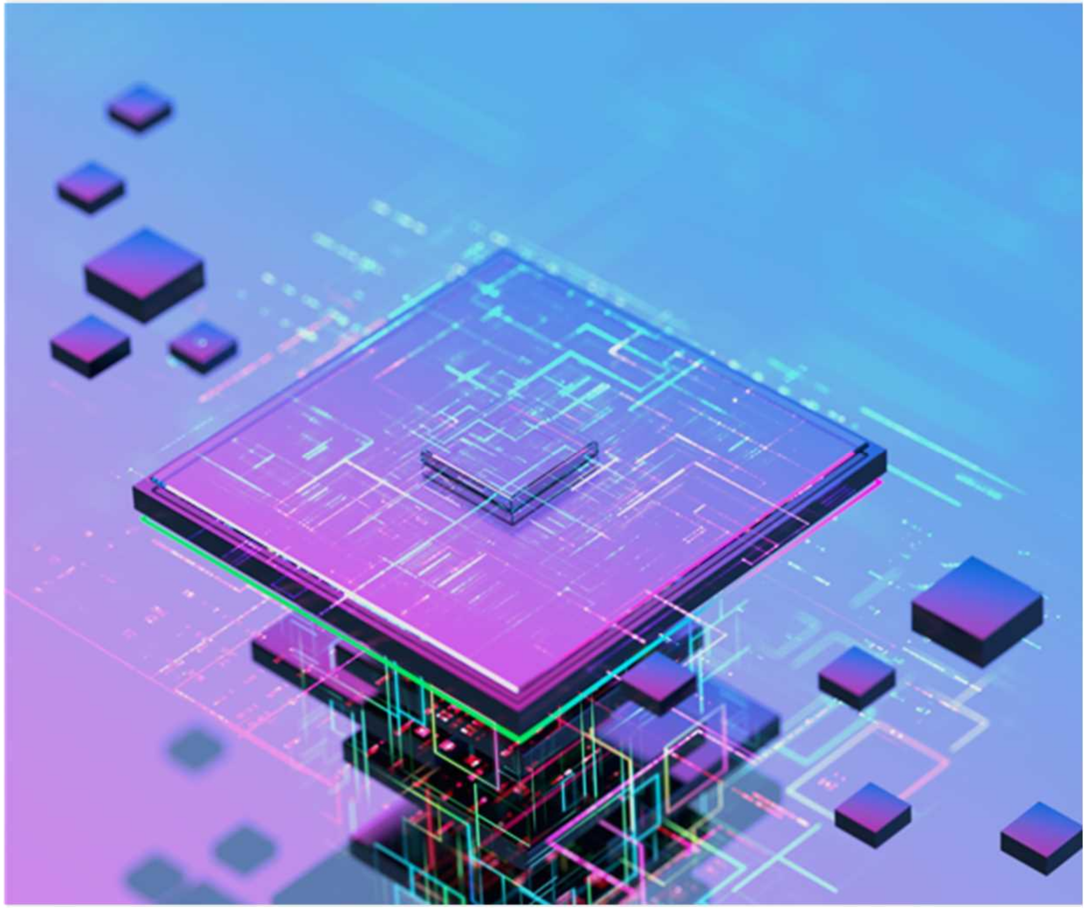
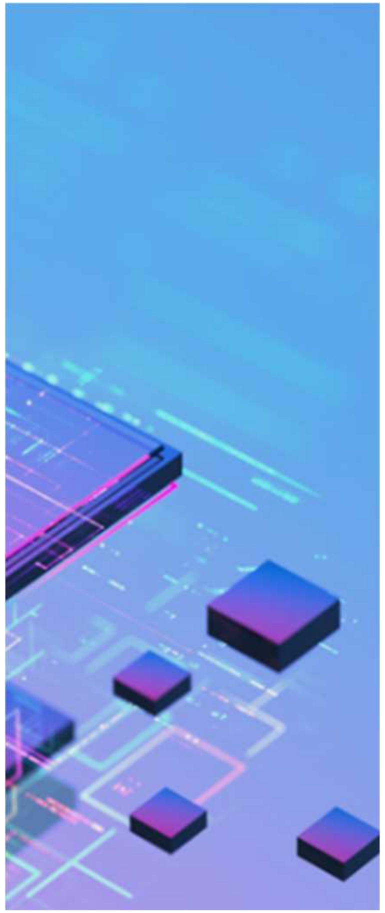


ULVAC, Inc.

The First Half of FY2025/6
Business Results

July 2024 - December 2024

February 12, 2025



Disclaimer regarding forward-looking statements etc.

Forward-looking statements

Forward-looking statements of the company in this presentation are based on information that was available at the time these documents were prepared. There are several factors that directly or indirectly impact the company performance, such as the global economy; market conditions for FPDs, semiconductor, electronic devices, and raw Materials; trends in capital expenditures and fluctuations in exchange rates. Please note that actual business results may differ significantly from these forecasts and future projections.

Processing of numbers

Figures and percentages in this document have been rounded to the nearest unit.

Product Category Change

From FY25/6, the name of “FPD production equipment” has been changed to “Display and Energy-Related Production Equipment”.

This document has been translated from the Japanese initial for reference purposes only. In the event of any discrepancy between this translated document and the Japanese initial, the initial shall prevail.

Summary

- Net sales and profit items for H1 exceeded both the plan and the previous H1, resulting in increased Net sales and profit. Although orders received decreased YoY, an increase is expected in H2 compared to H1.

- The profit margin base is steadily rising, with the Gross profit for Q2 reaching ¥23.8 billion, marking the highest level on a quarterly basis since listing.

- There are no changes to the consolidated earnings forecast for Net sales and each profit item, while the full-year Order received forecast has been revised
⇒ We will closely monitor the market environment and accurately capture investment trends to aim for an overall expansion in orders.

FY25/6 H1 Financial Highlights

ULVAC

(Unit: ¥1 billion)	FY2024/6						FY2025/6					
	Q1	Q2	H1	Q3	Q4	Full Year	Q1	Q2	H1 Plan	H1 Actual	YoY	
Orders Received	78.0	56.1	134.0	55.6	68.5	258.2	50.9	65.5	134.0	116.4	-17.6	-13%
Net Sales	55.0	65.2	120.2	65.0	75.9	261.1	61.0	73.9	129.0	134.9	+14.7	+12%
Gross Profit	15.3	20.1	35.4	22.0	23.3	80.7	19.1	23.8	-	42.9	+7.5	+21%
Gross Profit Margin	27.7%	30.8%	29.4%	33.8%	30.7%	30.9%	31.3%	32.2%	-	31.8%	+2.4pt	
SG&A	12.4	12.6	25.0	11.9	13.9	50.9	13.4	14.2	-	27.6	+2.6	+10%
Operating Profit	2.8	7.5	10.3	10.1	9.4	29.8	5.8	9.6	14.0	15.3	+5.0	+49%
Operating Profit Margin	5.1%	11.5%	8.6%	15.5%	12.3%	11.4%	9.4%	13.0%	10.9%	11.4%	+2.8pt	
Profit attributable to owners of parent	1.1	5.7	6.9	6.4	6.9	20.2	3.7	6.7	9.0	10.4	+3.5	+51%
To net sales ratio	2.1%	8.8%	5.7%	9.9%	9.1%	7.7%	6.1%	9.0%	7.0%	7.7%	+2.0pt	

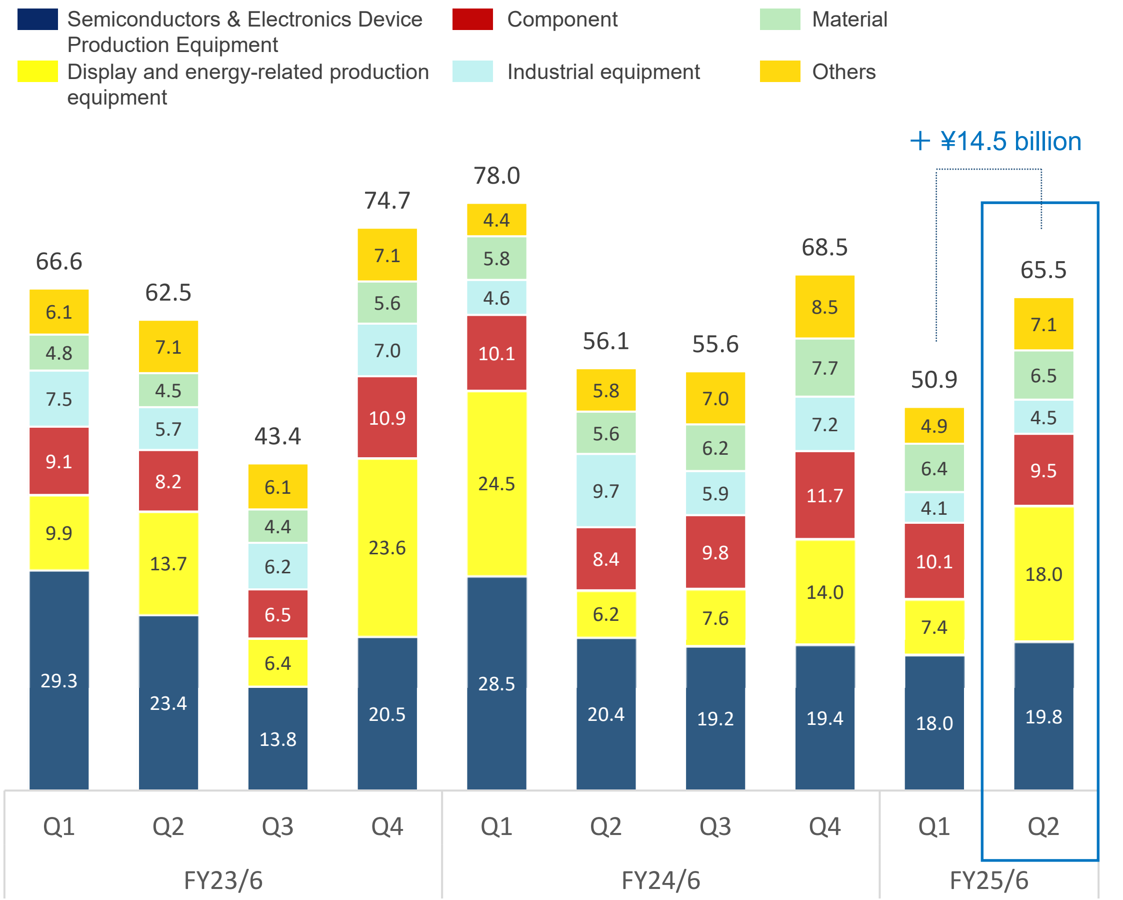
» Both Net sales and profit increased YoY, with the Gross profit margin rising steadily to 31.8%.

» All items improved QoQ.

Quarterly Trends

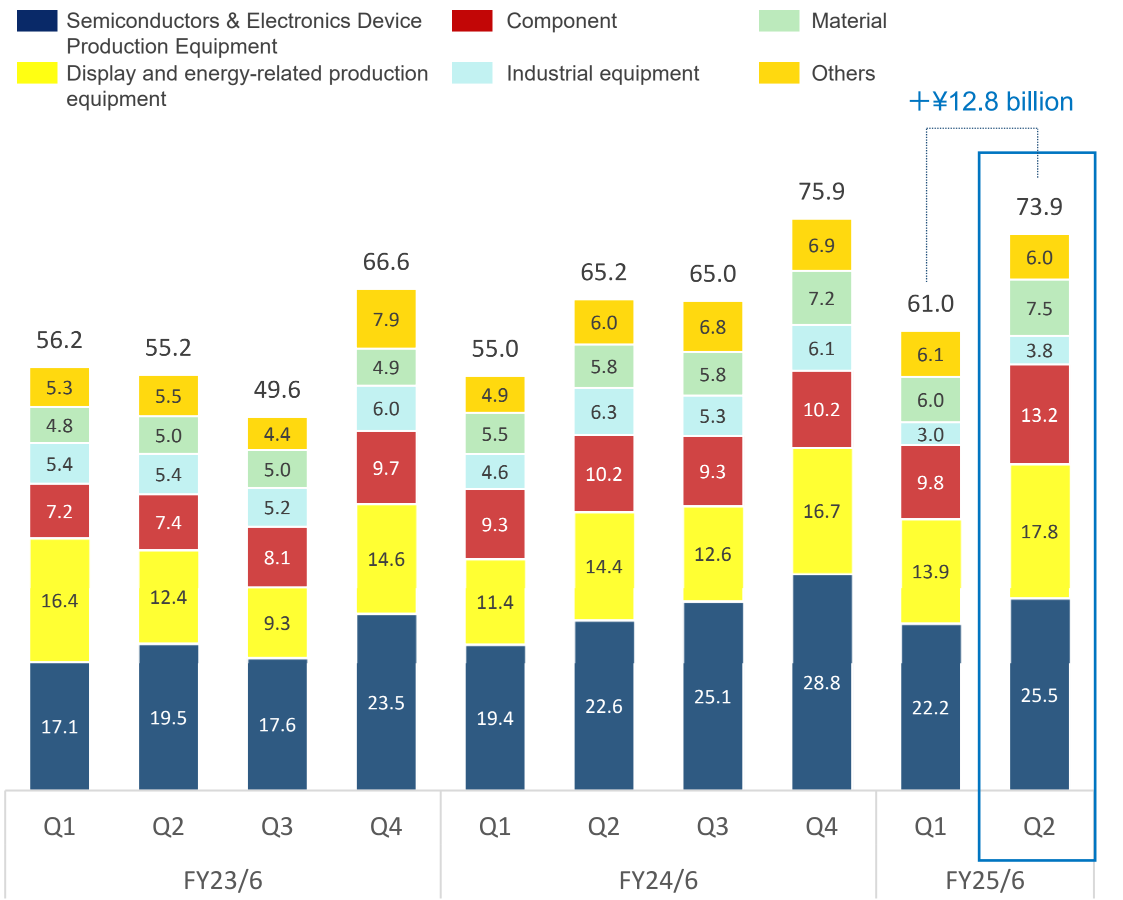
ULVAC

Orders Received (Unit: ¥1 billion)



	FY23/6 Q1	FY23/6 Q2	FY23/6 Q3	FY23/6 Q4	FY24/6 Q1	FY24/6 Q2	FY24/6 Q3	FY24/6 Q4	FY25/6 Q1	FY25/6 Q2
Semiconductors & Electronics Device Production Equipment	29.3	23.4	13.8	20.5	28.5	20.4	19.2	19.4	18.0	19.8
Display and energy-related production equipment	9.9	13.7	6.4	23.6	24.5	6.2	7.6	14.0	7.4	18.0
Component	9.1	8.2	6.5	10.9	10.1	8.4	9.8	11.7	10.1	9.5
Industrial equipment	7.5	5.7	6.2	7.0	4.6	9.7	5.9	7.2	4.1	4.5
Material	4.8	4.5	4.4	5.6	5.8	5.6	6.2	7.7	6.4	6.5
Others	6.1	7.1	6.1	7.1	4.4	5.8	7.0	8.5	4.9	7.1
Total	66.6	62.5	43.4	74.7	78.0	56.1	55.6	68.5	50.9	65.5

Net Sales (Unit: ¥1 billion)



	FY23/6 Q1	FY23/6 Q2	FY23/6 Q3	FY23/6 Q4	FY24/6 Q1	FY24/6 Q2	FY24/6 Q3	FY24/6 Q4	FY25/6 Q1	FY25/6 Q2
Semiconductors & Electronics Device Production Equipment	17.1	19.5	17.6	23.5	19.4	22.6	25.1	28.8	22.2	25.5
Display and energy-related production equipment	16.4	12.4	9.3	14.6	11.4	14.4	12.6	16.7	13.9	17.8
Component	7.2	7.4	8.1	9.7	9.3	10.2	9.3	10.2	9.8	13.2
Industrial equipment	5.4	5.4	5.2	6.0	4.6	6.3	5.3	6.1	3.0	3.8
Material	4.8	5.0	5.0	4.9	5.5	5.8	5.8	7.2	6.0	7.5
Others	5.3	5.5	4.4	7.9	4.9	6.0	6.8	6.9	6.1	6.0
Total	56.2	55.2	49.6	66.6	55.0	65.2	65.0	75.9	61.0	73.9

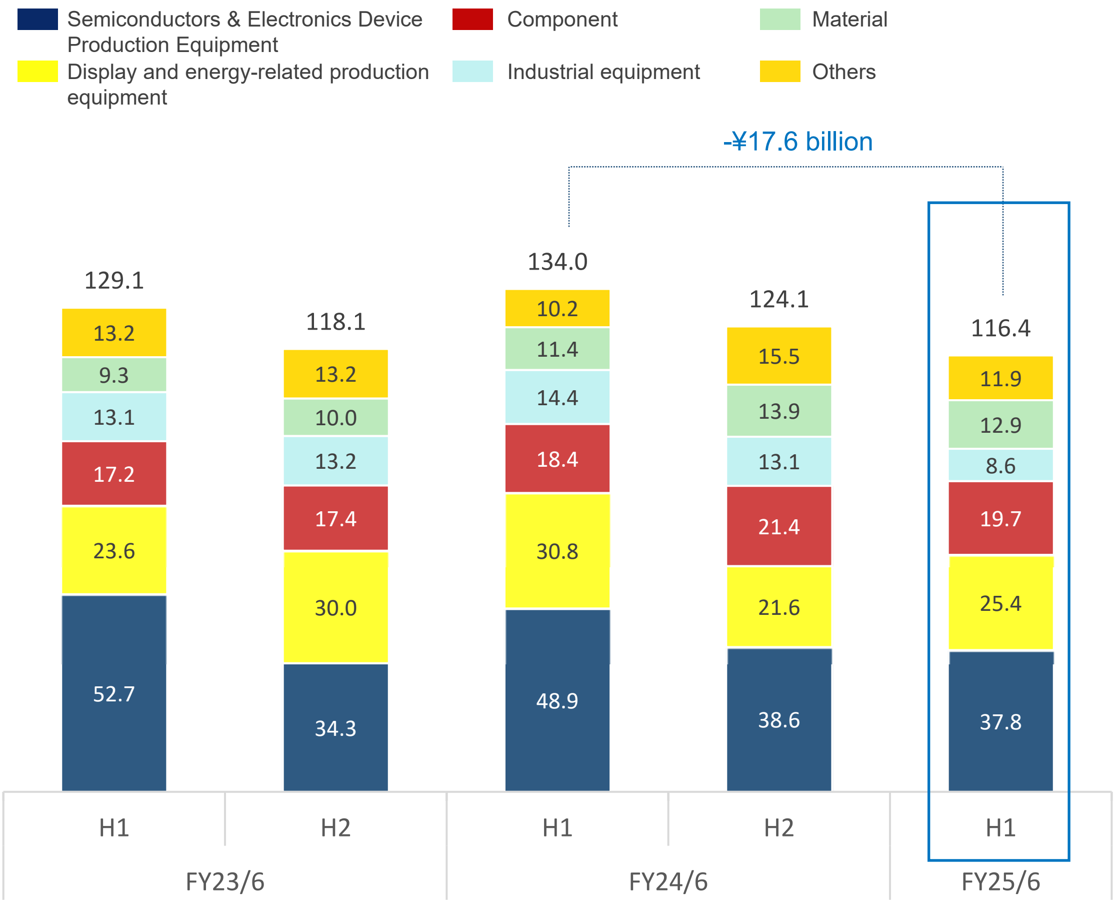
- » Orders received: Increased by ¥14.5 billion QoQ due to orders for OLED (G8.7) projects and others such as surface analysis equipment.
- » Net sales: Increased by ¥12.8 billion QoQ due to the high level of backlog orders that contributed to an overall increase across each item

Semiannual Trends

ULVAC

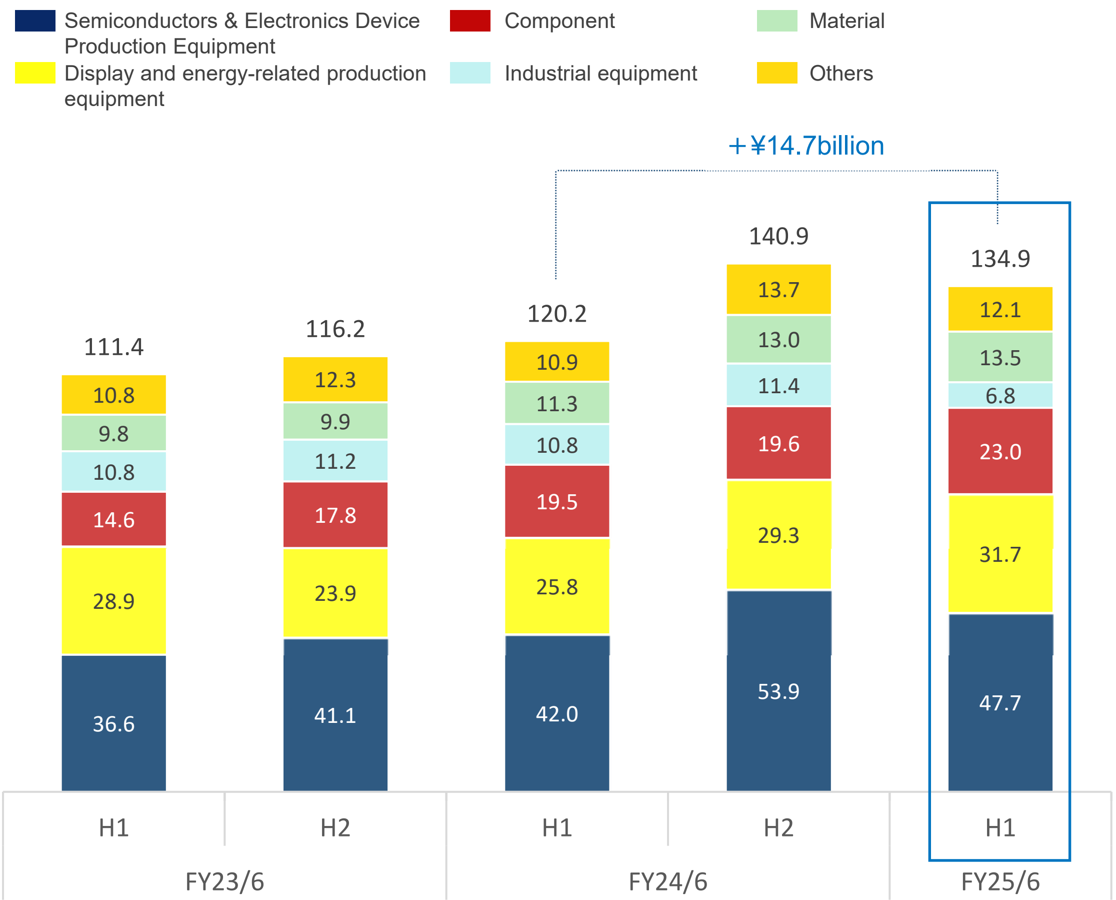
Orders Received

(Unit: ¥1 billion)



Net Sales

(Unit: ¥1 billion)



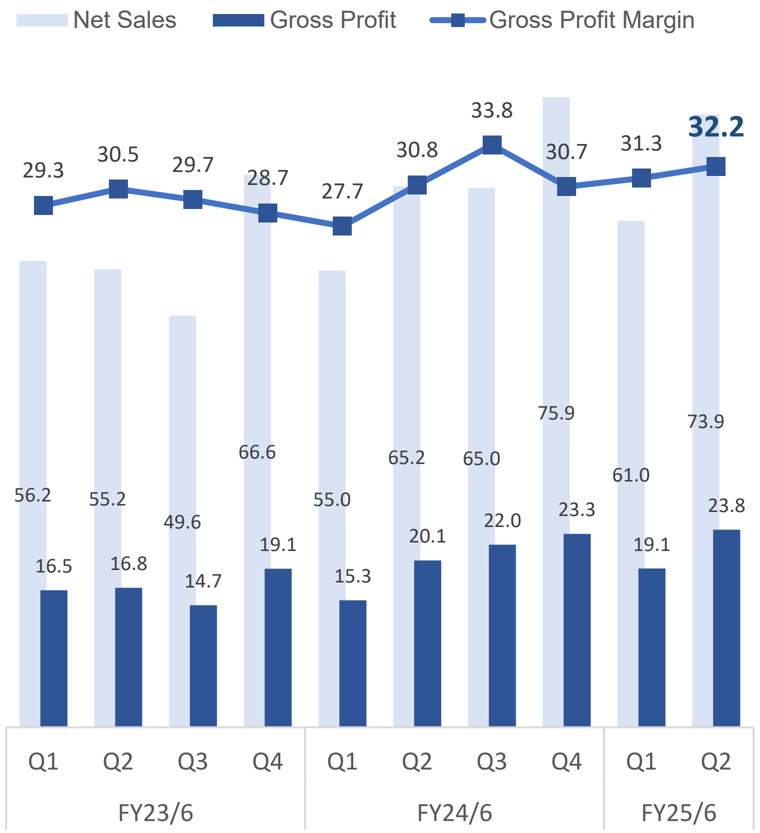
» Orders received: Decreased by ¥17.6 billion compared to the previous H1, due to a reactionary decline in power devices, batteries, etc.

» Net sales: Increased by ¥14.7 billion compared to the previous H1, as revenue recognition progressed steadily, resulting in an overall increase across each item.

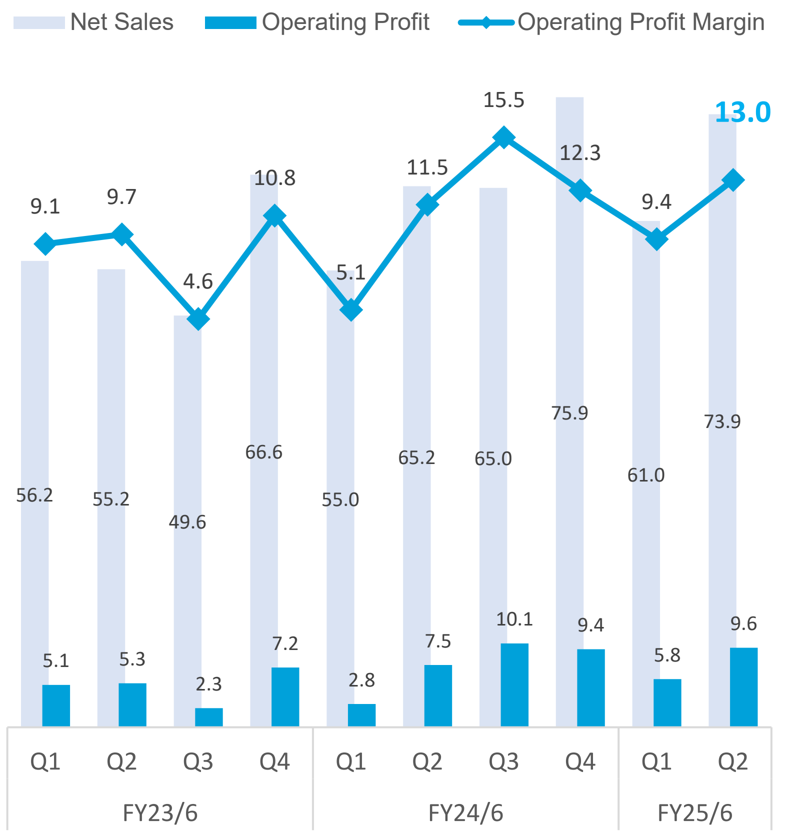
Profit Margin Trends

ULVAC

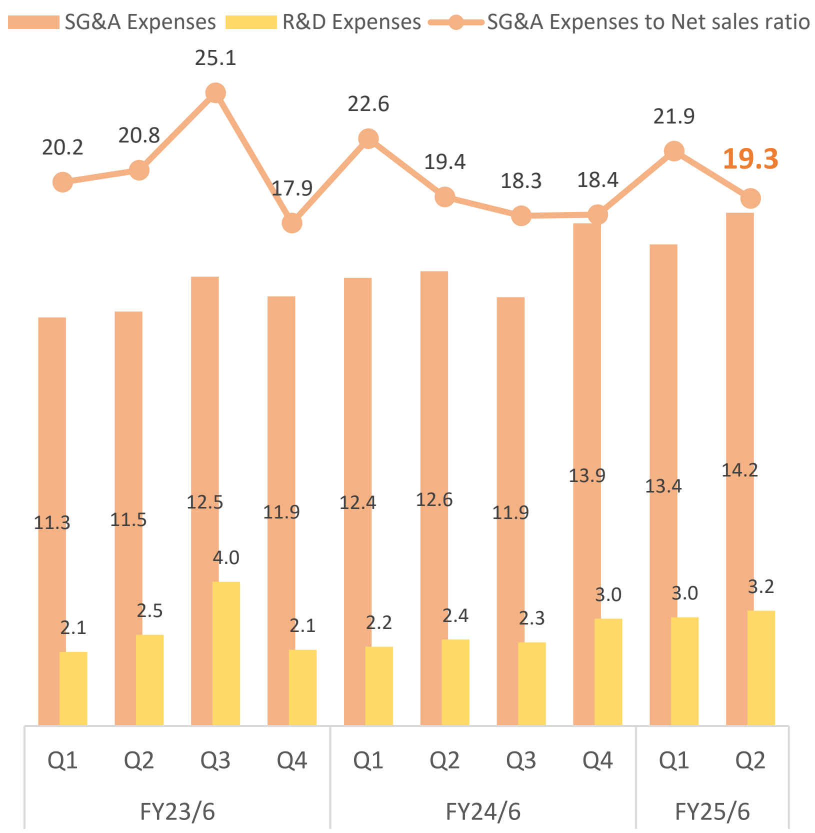
Gross Profit Margin
(Unit: ¥ 1 billion, %)



Operating Profit Margin
(Unit: ¥ 1 billion, %)



S.G.&A. Expenses
(Unit: ¥ 1 billion, %)



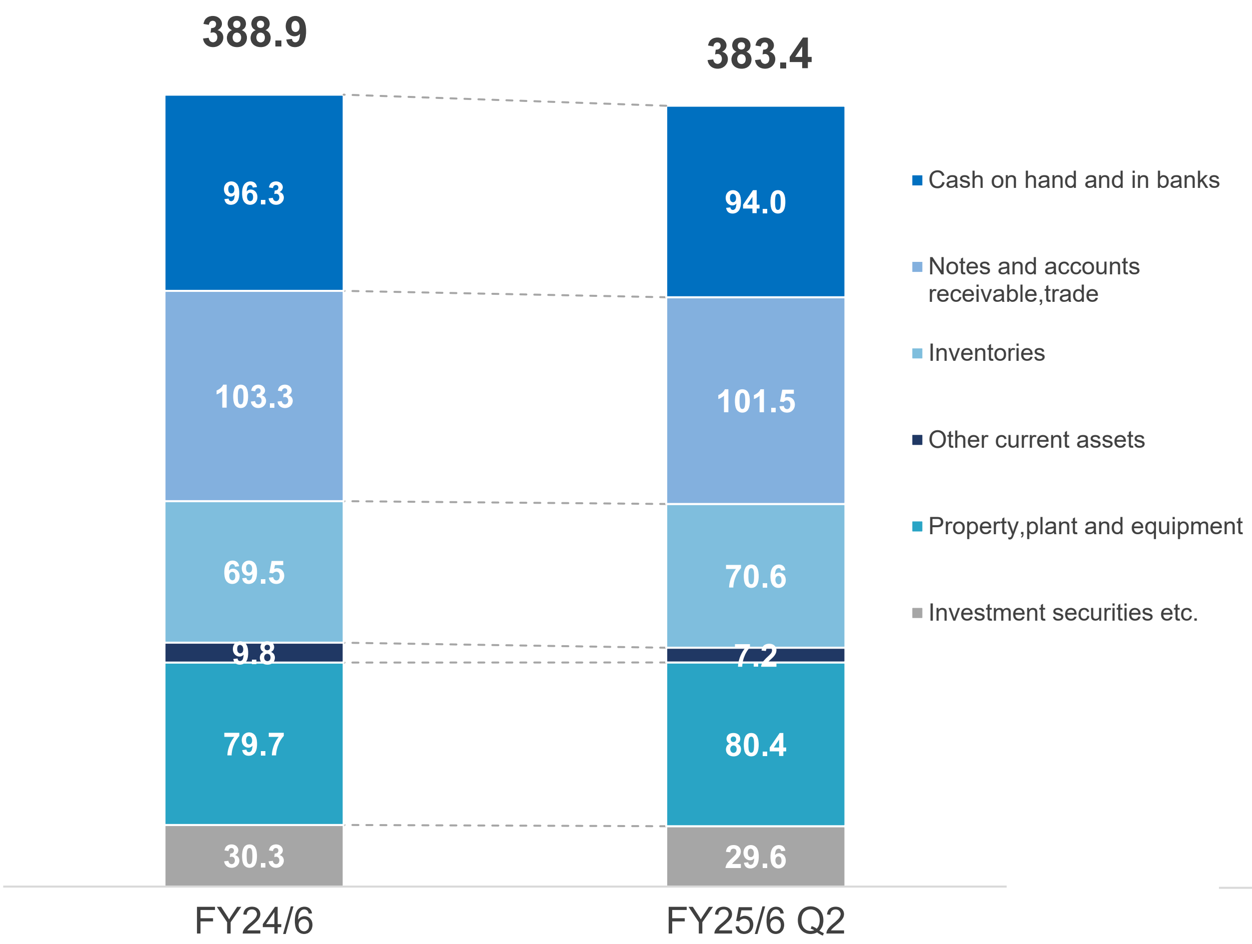
» Gross Profit Margin: In addition to the Net sales increase QoQ, the sales composition ratio of high-margin Semiconductors and Electronics/ Components continues to exceed 50%, with the profit margin base steadily rising.

» Operating Profit Margin: +3.6 pt. QoQ mainly due to the increased revenue.

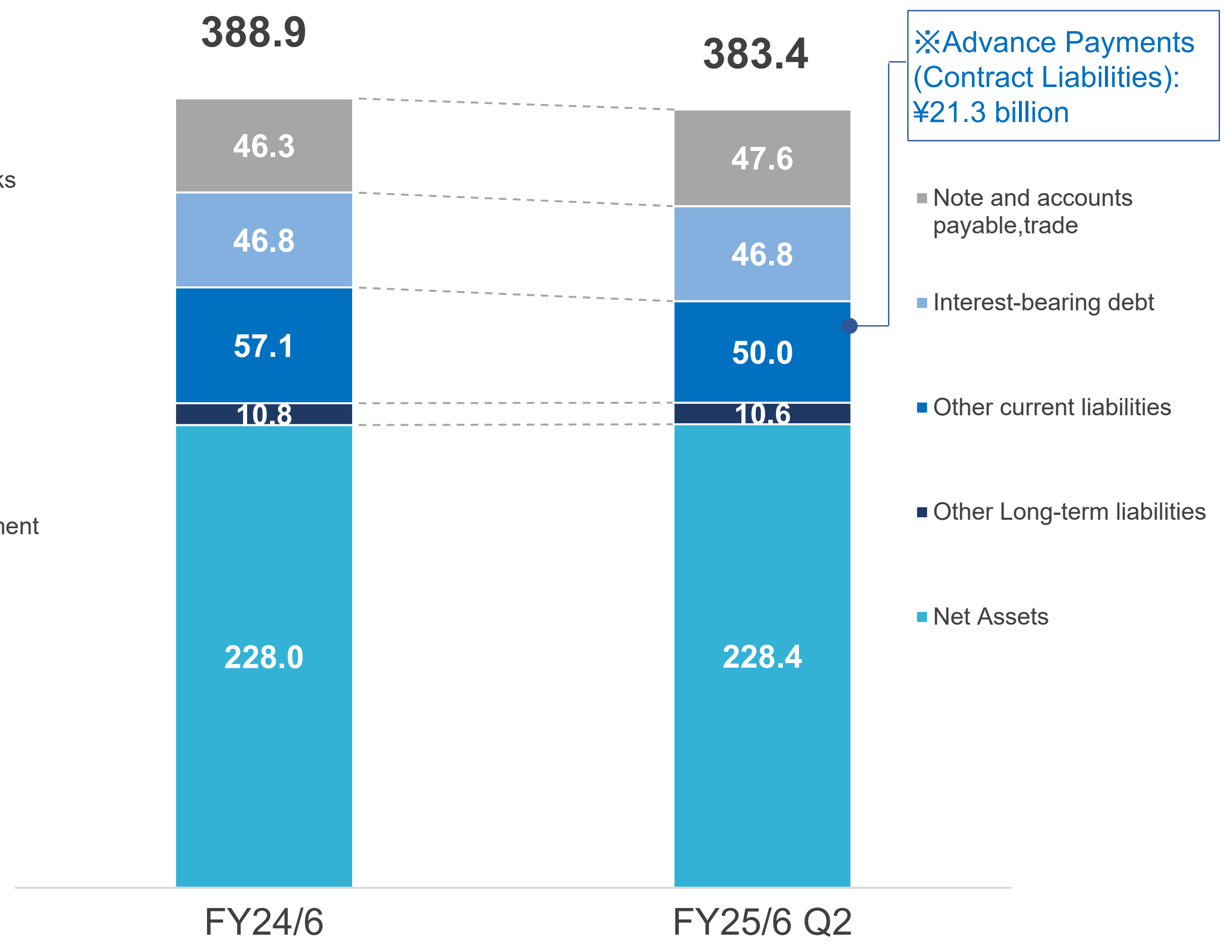
Consolidated Balance Sheet

ULVAC

Assets (Unit: ¥1 billion)



Liabilities and Net Assets (Unit: ¥1 billion)



FY25/6　Earnings Forecast

ULVAC

(Unit: ¥1 billion)	FY 24/6 Full Year Actual	H1 Actual	H2 Forecast	FY 25/6 Full Year Forecast	YoY Amount	YoY %
Orders Received	258.2	116.4	143.6	Previous※ 270.0	+11.8	+5%
				Current 260.0	+1.8	+1%
Net Sales	261.1	134.9	140.1	275.0	+13.9	+5%
Operating Profit	29.8	15.3	19.2	34.5	+4.7	+16%
Operating Profit Margin	11.4%	11.4%	13.7%	12.5%	+1.1pt	-
Profit attributable to owners of parent	20.2	10.4	12.6	23.0	+2.8	+14%
To net sales ratio	7.7%	7.7%	9.0%	8.4%	+0.6pt	-
Dividend per share(Yen)	144.0			164.0	+20.0	

※Disclosed on 13 Aug 2024

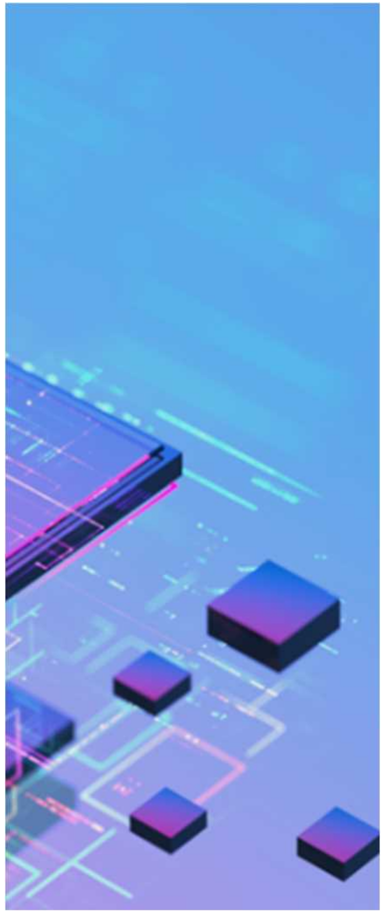
Semiconductor and Electronics
- Power Devices: -¥6.0 billion

Display & Energy
- Battery: -¥2.0 billion

Industrial Equipment
- High-performance Magnet Manufacturing Equipment, etc.: -¥2.0 billion

» Orders received: Full year forecast revised to ¥260 billion, reflecting the slowdown in EV demand, etc.

» Net sales and Profit (Margin): The earnings forecast remains unchanged, supported by contributions from the order backlog (¥125.5 billion at the end of Q2).



Market Environment and Future Business Development

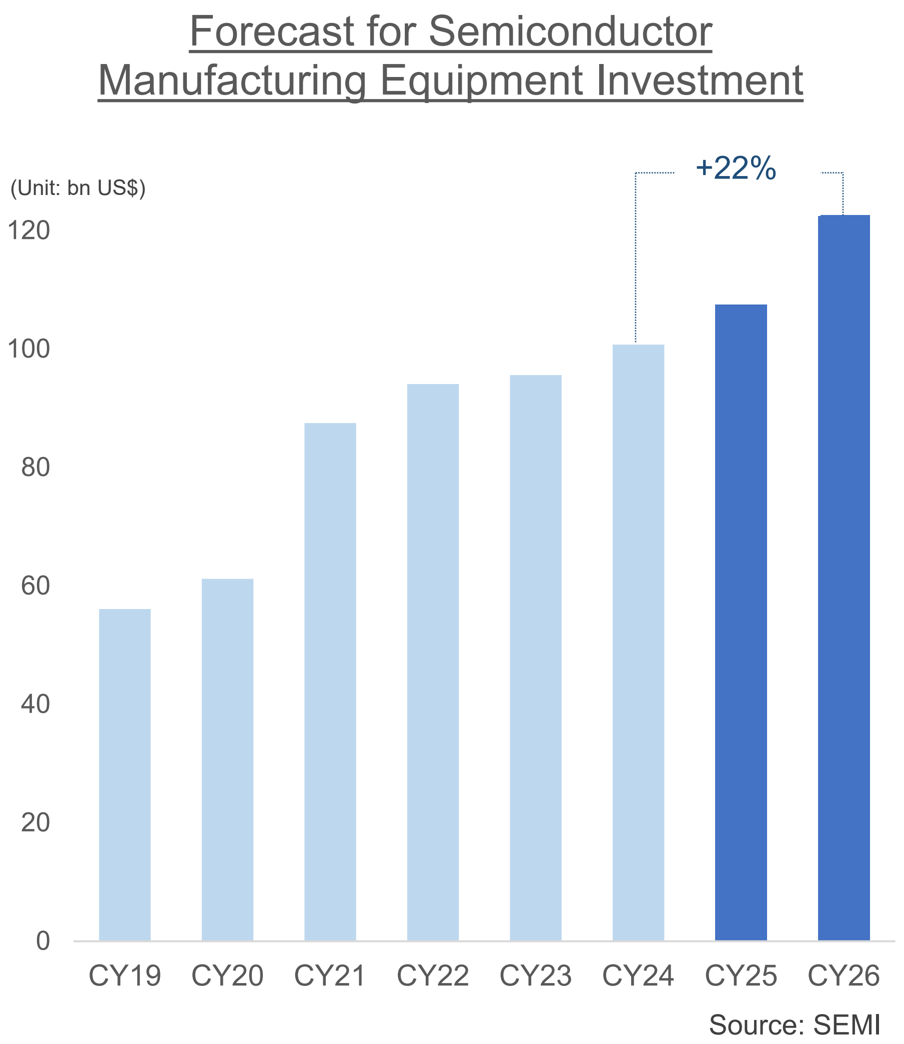
Market environment and investment trends

ULVAC

Category	Market Environment and Investment Trends	CY25	CY26
Semiconductor Logic & Memory	• DRAM: Investment is accelerating due to the expanding demand for generative AI. • NAND: Inventory adjustments are progressing, leading to a resumption of investment. • Advanced Logic: Investment is intensifying towards next-generation nodes.		
Various Electronic Devices	• The expansion of generative AI demand is activating the advanced packaging business. • Continued investment in technological innovation and production expansion		
Power Devices	• Although the current investment is slowing due to a decline in EV demand, medium- to long-term growth is expected.		
Display	• Investment in OLED (G8.7) for IT panels is becoming more active. • Additional equipment and modification projects are expected to contribute for higher definition in LCD and OLED (G6).		
Battery-related	• The timing of adopting next-generation batteries for automotive use is showing a tendency to delay, while medium- to long-term growth is expected.		
Components, General Industry, Materials, and Others	• Progressing steadily as a stable base business due to the recovery of semiconductor-related investments. • Leak test equipment for new applications such as cooling systems in AI servers is expected to expand. • Surface analysis equipment is in high demand due to active research and development of advanced devices.		

» We will closely monitor the market environment and accurately capture investment trends to aim for an overall expansion in orders.

Semiconductor Market Environment



- Expansion of production capacity due to increased demand for AI semiconductors
- Technological innovation through the introduction of cutting-edge technology and new device structures to achieve miniaturization, speed enhancement, and energy efficiency
- Increased investment for building regional supply chains

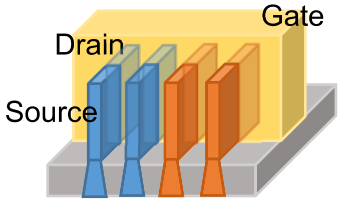
Expectations for medium- to long-term growth

Advanced Logic

ULVAC

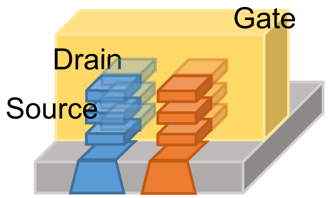
Changes in Logic Device Structure

3nm Generation



Fin structure

Beyond the 2nm Generation



Sheet structure

Expansion of business opportunities for advanced logic due to technological innovation (miniaturization)

- Expansion of MHM (Metal Hard Mask) application
  - Expansion of 5nm and 3nm processes
  - Expansion of application in DUV exposure in addition to EUV exposure
  - Application of TiN, a metal material of MHM, as an electrode material

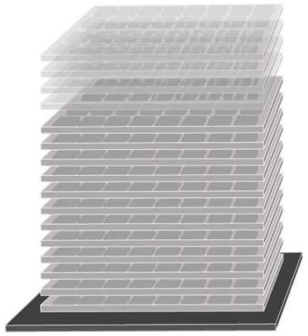
- Transition from Fin structure to Sheet structure with the advancement of the 2nm generation
  - Expectation for the expansion of new Hardmask for diffusion processes
  - Adaptation to backside wiring

- Expansion of POR acquisition through joint development with key customers in other metal processes, etc. (expectation as a strong second vendor)

Advanced Memory & Packaging

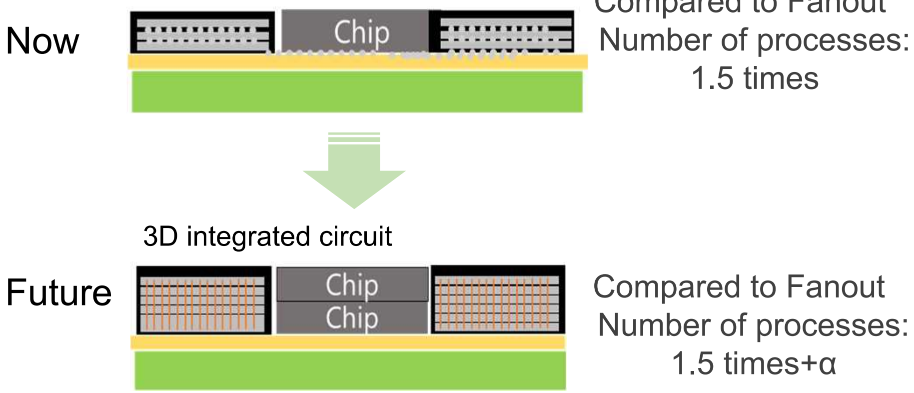
Advanced memory

High Bandwidth Memory



Advanced packaging

Chip on Interposer on Substrate



Growth through expansion of production capacity and technological innovation progress due to increased demand for AI semiconductors

Advanced Memory

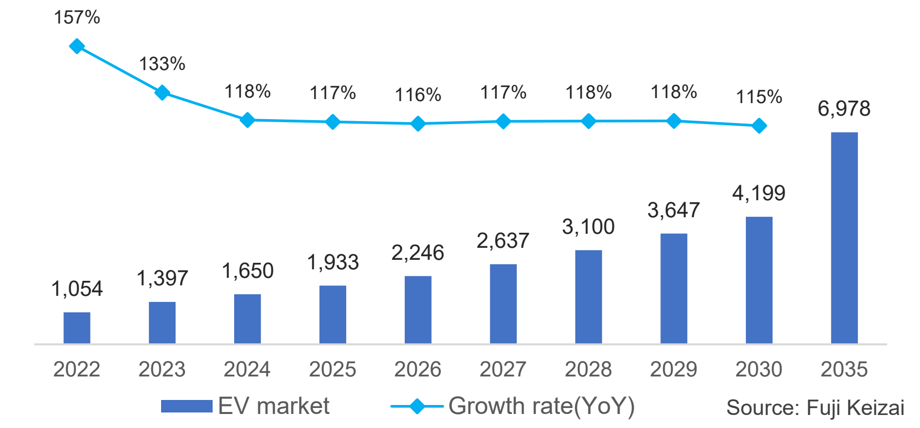
- - Expansion of investment in conventional DRAM (DDR5) due to increased demand for HBM
  - Progress in DRAM miniaturization through the application of TiN MHM
- Active investment for next-generation NAND
- Expansion of POR acquisition through joint development with key customers in other metal processes, etc. (expectation as a strong second vendor)

Advanced Packaging

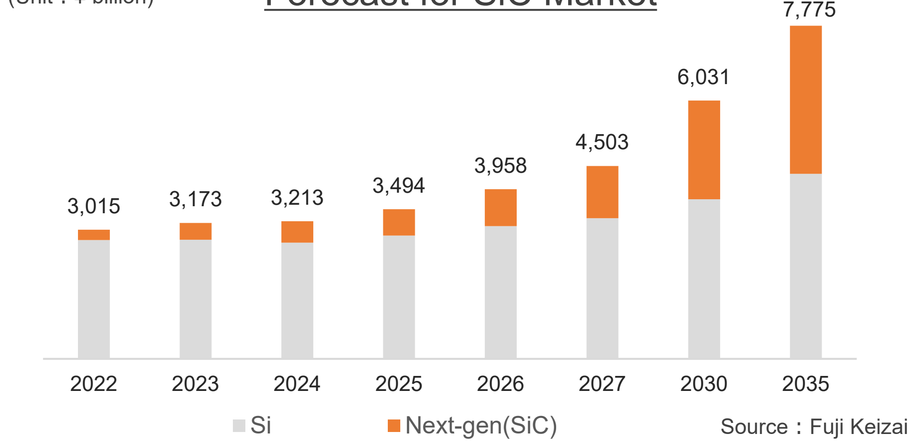
- Active investment in descum processing equipment for interposers
- Continued development of sputtering equipment, descum/desmear processing equipment, plasma dicing, etc., for next-generation advanced packaging

Power devices

Forecast for EV Market



Forecast for SiC Market



Significant growth in the SiC market with the recovery of the EV market

Expansion of sales in Japan and China with the increase in wafer size (6→8 inch)

Cross-selling of sputtering equipment in Japan and ion implantation equipment in China both having a high market share in each region

NEW

- Expansion of SiC compound etching equipment with the switch from planar to trench structure
- Market introduction of GaN compound sputtering equipment → Capturing future demand

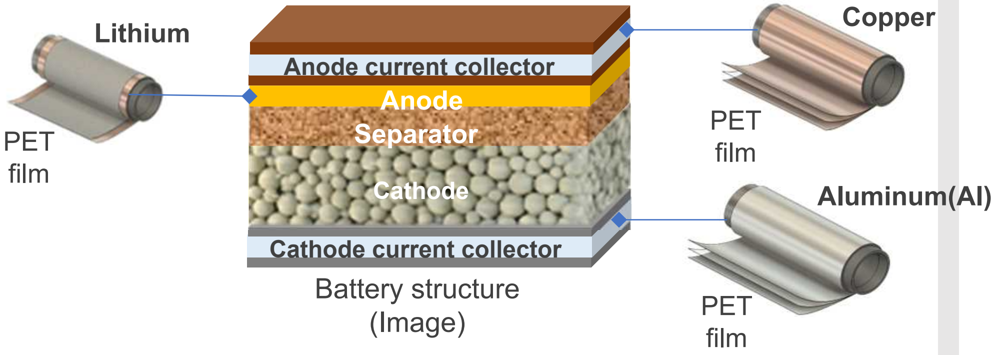
Battery Related

Merits of Double-sided evaporation film current collectors

1. Safety improvement
2. Reduction of size and weight
3. Reduction of material costs
4. GHG reduction

Supply Chain

- ULVAC, Inc. [Evaporation Roll to Roll equipment]
- Material processor [Battery Components]
- Battery manufacturer [Battery]
- EV Makers [Electric vehicles]



Battery structure (Image)

Growth through the spread of aluminum double-sided evaporation film technology aimed at improving safety and achieving miniaturization and weight reduction

Improvement through continued customer support for stabilizing production of current models

Continued development of mass production technology for the model with wider film width aimed at improving productivity

NEW

- Continued development of copper thick film deposition aimed at replacing the anode current collector
- Continued development of next-generation battery anodes (lithium)

Topics

Launch of new deposition equipment model for semiconductors

Designing on the features of the previous model, we have begun taking orders for the next-generation platform "ENTRON-EXX," which enhances data collection, analysis capabilities, and scalability.

- 20% reduction in power consumption in standby mode
- Up to 10% reduction in installation floor space within clean rooms
- Improved productivity through real-time data analysis
- Design allows for rapid module additions to flexibly meet changing needs ⇒ 50% reduction in relocation and modification lead time

Contributing to the development of the semiconductor industry through vacuum technology

Topics

Collaboration with Silicon Austria Labs GmbH (SAL) Development of plasma etching technology for mass production processes of thin-film lithium niobate (TFLN)

TFLN is a next-generation optical device material with characteristics of wide bandwidth, low loss, and high efficiency, meeting the demand for data communication capacity

SAL has introduced the plasma etching system "NLD-5700" for forming optical waveguides inside optical devices, aiming to enhance material integration and scalability on a 200mm platform.

This collaboration promotes technological innovation and contributes to the entire microelectronics ecosystem

SAL SILICON AUSTRIA LABS

Silicon Austria Labs GmbH (SAL) connects ideas to innovation by producing consistent research results and economic impact in the fields of microsystems, sensor systems, intelligent wireless systems, power electronics, and embedded systems.

Here & There, Near your side

AI
Artificial Intelligence (AI)
Semiconductor
Electronic Device

- SED
- AEED
- Component
- Material

Hospital
IoT Vaccine
Telemedicine
Sterile products

- SED
- AEED
- FPD
- IED
- Components
- Material

Data center
Data center
Semiconductor memory Logic
Power Device Electronic Device

- SED
- AEED
- Component
- Material

Electronic Vehicle
Electronic Vehicle Power device
Electronic Device
High-performance battery
Rare metal earth

- SED
- AEED
- FPD
- Component
- Material

Circuit Breaker
Circuit breaker
Heat Exchanger

- IED
- Components

Wind Power
Wind power
Power Devices
High-performance battery for electricity

- SED
- AEED
- IED
- Component
- Material

Smart home
Smart home
Semiconductor
Electric Device
Display

- SED
- AEED
- FPD
- Component
- Material

Freeze Dry Supplement
Freeze dry supplement

- IED
- Component

Drone
Drone
Smart Agriculture
Semiconductor
Electronic Device
Battery

- SED
- AEED
- Component
- Material

Solar Cell
Solar cell power plants
Power device for control

- AEED
- FPD
- Component
- Material

ULVAC